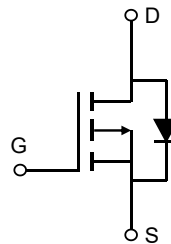


### Description

#### Features

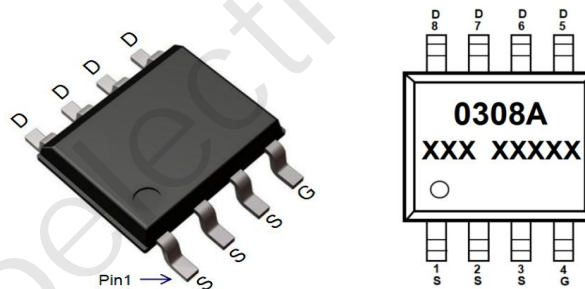
- -30V, -15A  
 $R_{DS(ON)}$  Typ = 8.3mΩ @  $V_{GS} = -10V$   
 $R_{DS(ON)}$  Typ = 12mΩ @  $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free
- 100% UIS TESTED!



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMPBL0308A	0308A	SOP-8	TAPING	13"	4000	40000

#### Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

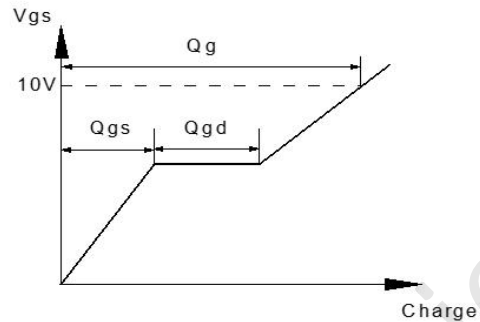
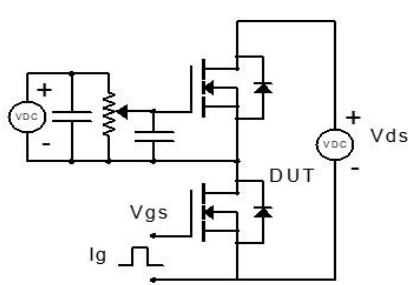
Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	-30	V
$V_{GS}$	Gate-to-Source Voltage	±20	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	-15
		$T_A = 100^\circ C$	-9
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	-60	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	64	mJ
$P_D$	Power Dissipation	$T_A = 25^\circ C$	4.1
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	30	°C/W
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

### Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

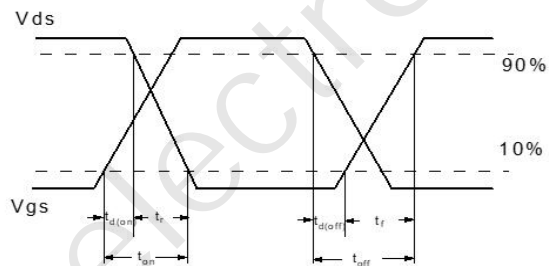
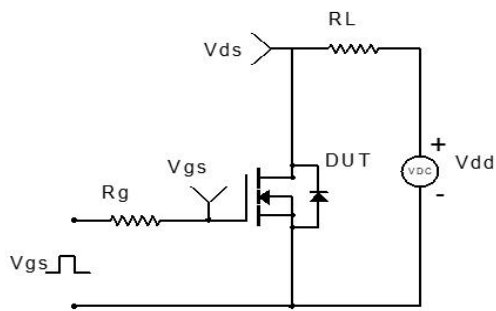
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = -250μA, V <sub>GS</sub> = 0V	-30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V	-	-	-1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.1	-1.5	-2.2	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(4)</sup>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -3A	-	8.3	10.8	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -2A	-	12	15.6	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -15V, f = 1MHz	-	1403	-	pF
C <sub>oss</sub>	Output Capacitance		-	250	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	217	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to -10V V <sub>DS</sub> = -15V, I <sub>D</sub> = -10A	-	25	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	4	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	5.5	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = -10V, V <sub>DD</sub> = -15V I <sub>D</sub> = -10A, R <sub>GEN</sub> = 3Ω	-	11	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	17	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	60	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	45	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-15	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-60	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = -3A	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> = -10A, di/dt = 100A/us	-	15	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	6	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2. E<sub>AS</sub> condition: Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=-15V, V<sub>G</sub>=-10V, R<sub>G</sub>=25ohm, L=0.5mH, I<sub>AS</sub>=-16A
  3. R<sub>θJA</sub> is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB
  4. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

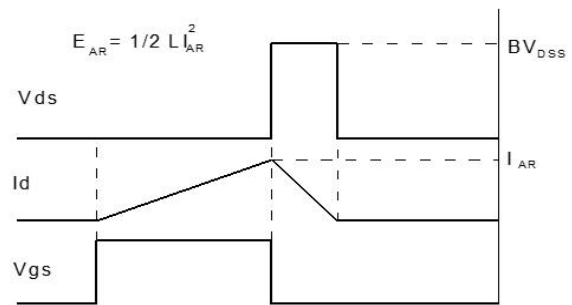
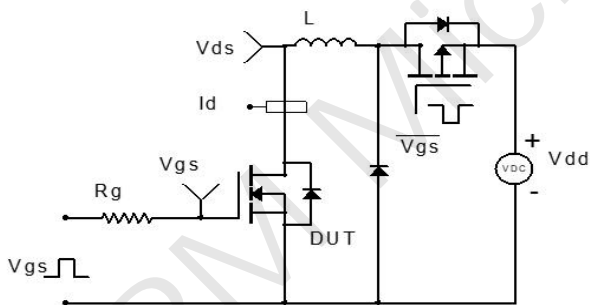
**Test Circuit**



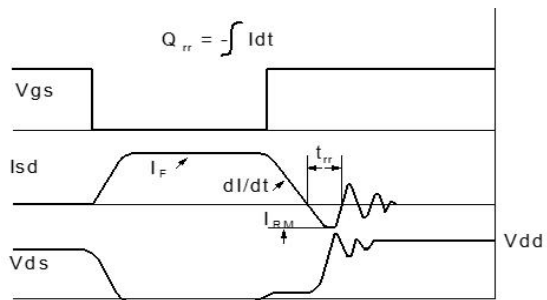
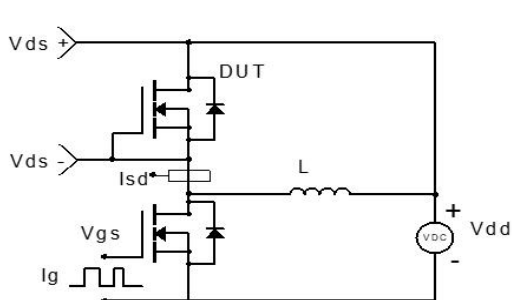
**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveform**

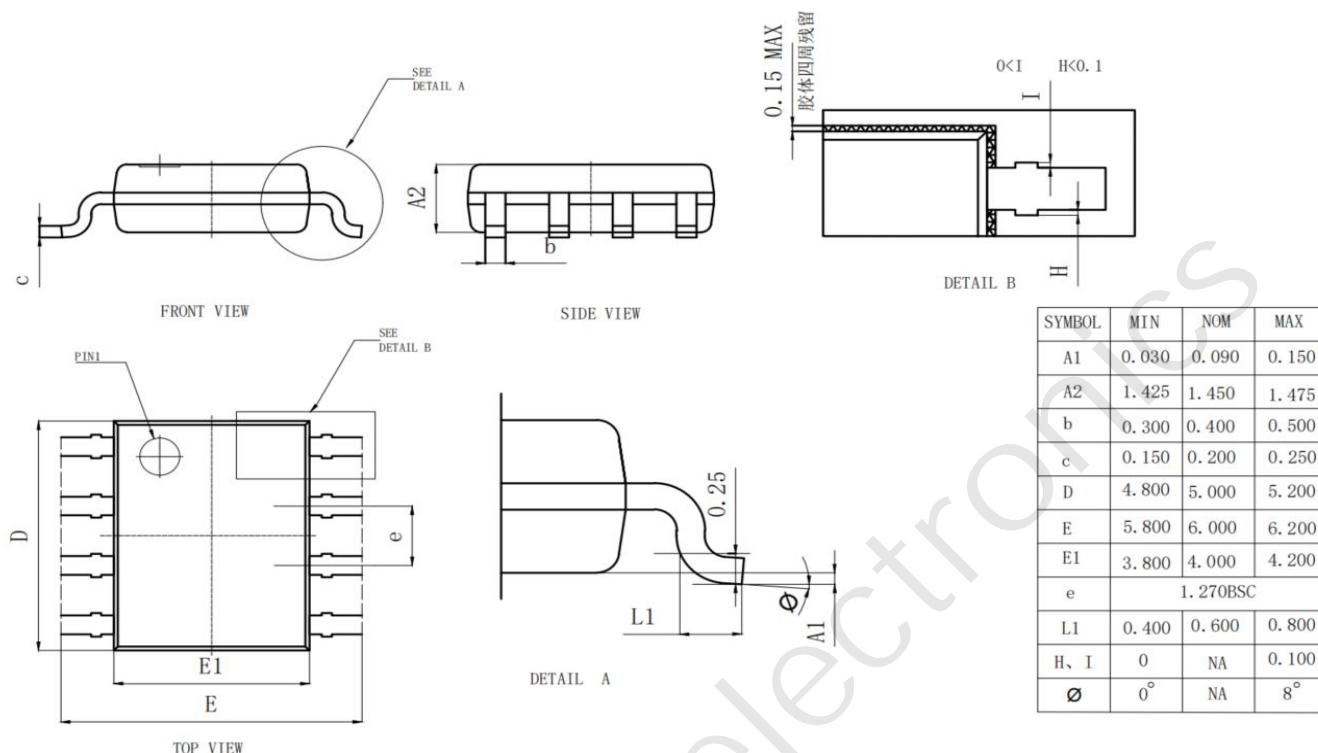


**Figure 3: Unclamped Inductive Switching Test Circuit & Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**

### Package Mechanical Data(SOP-8)




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